

In re Patent Application of:
PIKE ET AL.
Serial No. 09/741,754
Filed: December 19, 2000

In the Claims:

Claims 1-20 (cancelled)

21. (Original) An electronic device comprising:
a first member comprising silicon; and
a second member comprising a low temperature co-fired ceramic (LTCC) material;
said first and second members having opposing surfaces thereof anodically bonded together to form a hermetic seal therebetween.

22. (Original) An electronic device according to Claim 21 wherein said first and second members have opposing generally planar major opposing surfaces.

23. (Original) An electronic device according to Claim 21 wherein at least one of said first and second members comprises at least one cooling structure therein.

24. (Original) An electronic device according to Claim 21 wherein said first member further comprises at least one first micro-fluidic cooling structure therein.

25. (Original) An electronic device according to Claim 24 wherein said at least one first micro-fluidic cooling structure comprises an evaporator.

26. (Original) An electronic device according to Claim 24 wherein said second member further comprises at least

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one second micro-fluidic cooling structure aligned with the at least one first micro-fluidic cooling structure.

27. (Original) An electronic device according to Claim 26 wherein said at least one second micro-fluidic cooling structure comprises at least one micro-fluidic passageway.

28. (Original) An electronic device according to Claim 26 further comprising at least one integrated circuit adjacent said at least one second micro-fluidic cooling structure.

29. (Original) An electronic device according to Claim 28 wherein said at least one integrated circuit comprises electrical connections; and wherein the second member comprises external electrical connections connected to the electrical connections of said at least one integrated circuit.

30. (Original) An electronic device comprising:
a first member comprising silicon and having at least one first micro-fluidic cooling structure therein;
a second member comprising a low temperature co-fired ceramic (LTCC) material and having at least one second micro-fluidic cooling structure aligned with the at least one first micro-fluidic cooling structure of said first member;
said first and second members having opposing surfaces thereof anodically bonded together to form a hermetic seal therebetween; and

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at least one integrated circuit adjacent said at least one second micro-fluidic cooling structure.

31. (Original) An electronic device according to Claim 30 wherein said first and second members have opposing generally planar major opposing surfaces.

32. (Original) An electronic device according to Claim 30 wherein said at least one first micro-fluidic cooling structure therein comprises an evaporator.

33. (Original) An electronic device according to Claim 30 wherein said at least one second micro-fluidic cooling structure comprises at least one micro-fluidic passageway.

34. (Original) An electronic device according to Claim 30 wherein said at least one integrated circuit comprises electrical connections; and wherein the second member comprises external electrical connections connected to the electrical connections of said at least one integrated circuit.